



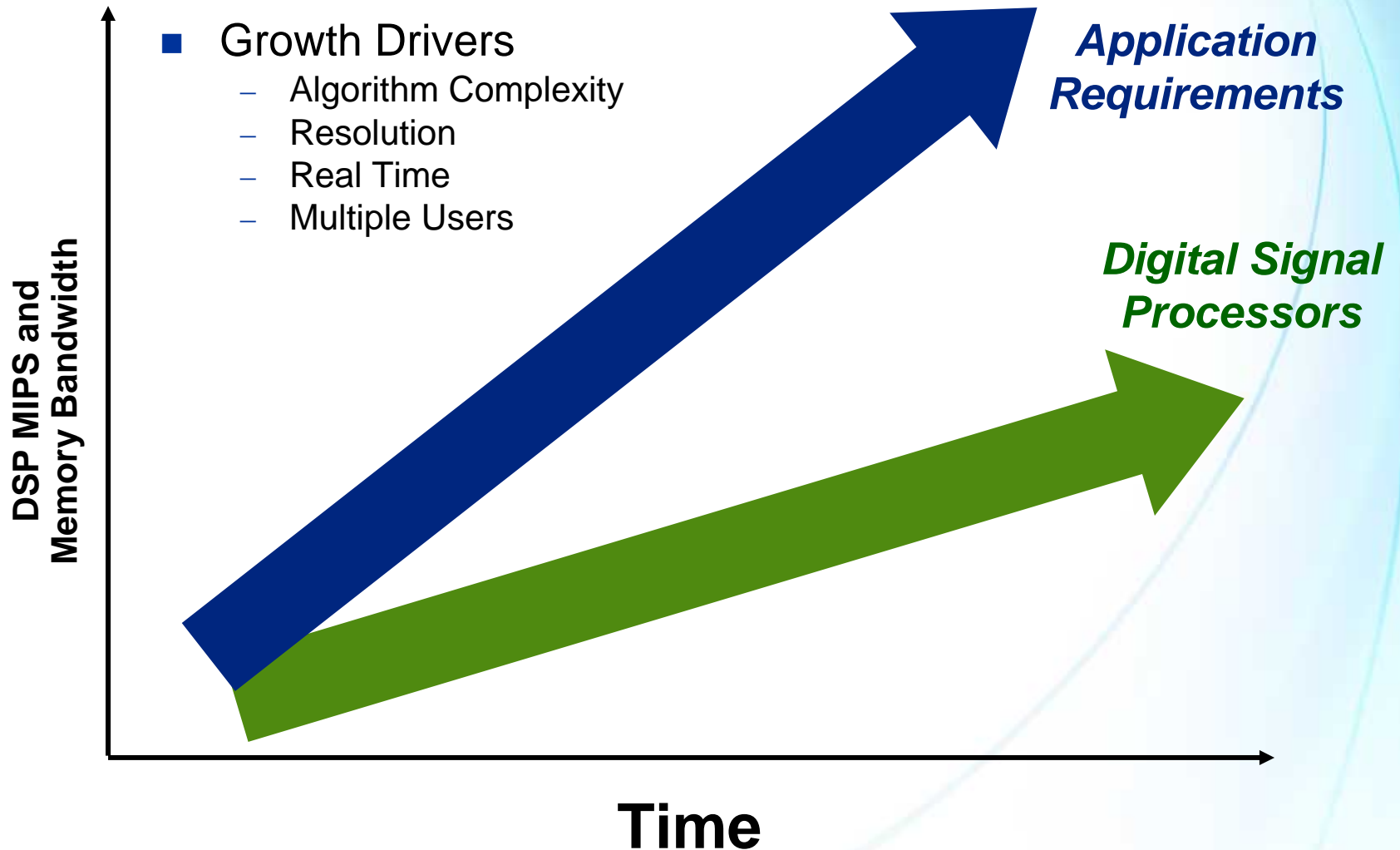
High-Performance Digital Signal Processing (DSP) Applications with Serial RapidIO Standard



Agenda

- High-performance DSP applications
- Serial RapidIO™ review
- Altera® Serial RapidIO solution
- Altera Serial RapidIO demo

Growing Demand for MIPS and Memory Bandwidth



DSP vs. FPGA Comparison – 1

| | DSP | FPGA |
|----------------------|---|--|
| Advantages | <ul style="list-style-type: none">■ High clock rate■ Rapid software development in C++ | <ul style="list-style-type: none">■ High number of instructions/clock■ High number of multipliers■ High bandwidth flexible I/O and memory connectivity |
| Disadvantages | <ul style="list-style-type: none">■ Limited number of instructions/clock■ Limited number of multipliers■ Limited memory and device connectivity | <ul style="list-style-type: none">■ Longer development time■ Typically lower clock rates |

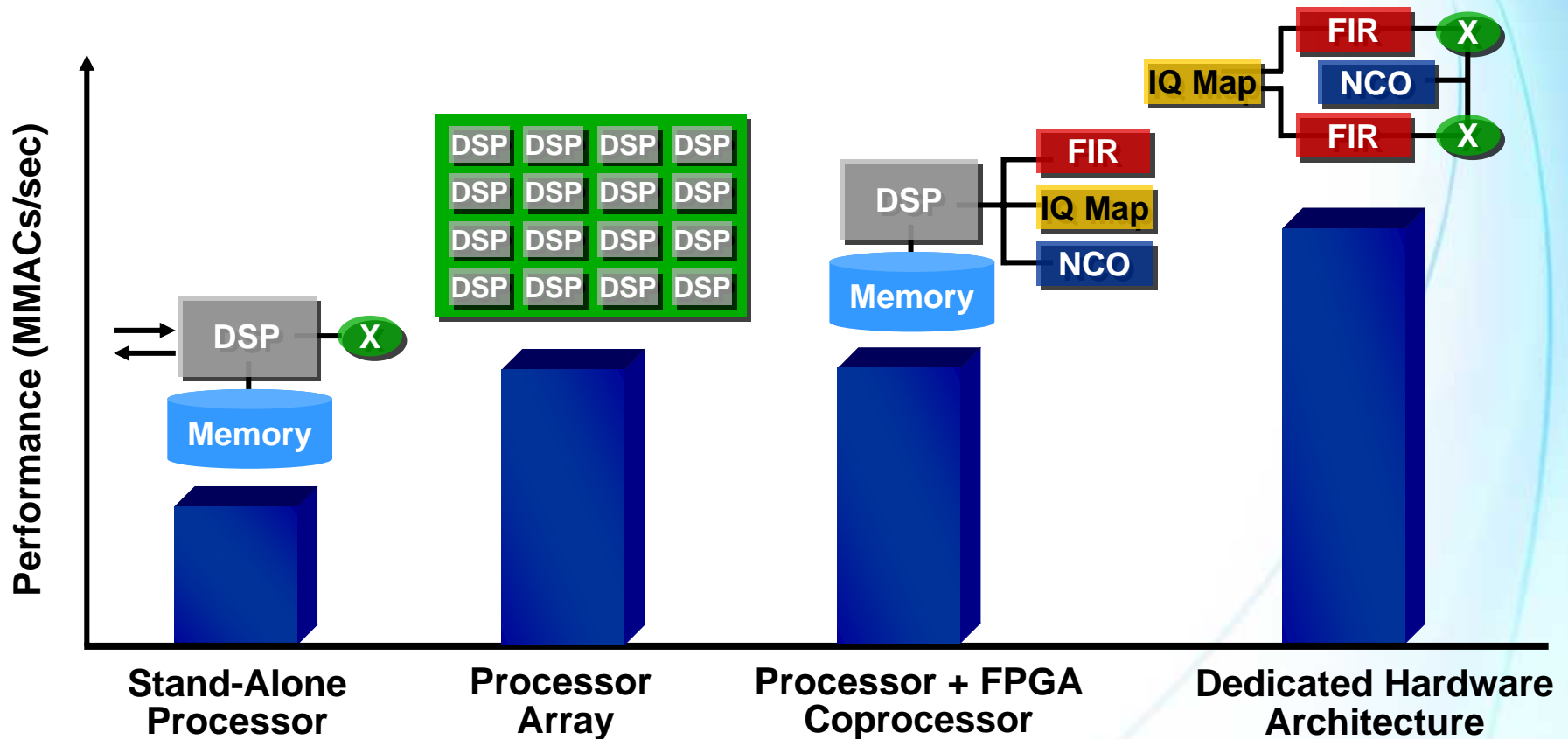
DSP vs. FPGA Comparison – 2

| Functions | DSP | FPGA |
|---|---------------------------------------|--|
| Maximum clock rate | 1 GHz | 370 MHz |
| Maximum number of multipliers | 4 (16-bit X16-bit) | Over 700 18-bit X 18-bit (384 HW + 300 LE) or over 1400 9-bit X 9-bit ¹ |
| Maximum number of instructions/clock | 4 or 8 | 100s to 1000s |
| Ease of programming | C,C++ software flow | HDL hardware flow |
| I/O flexibility | Limited | Flexible |
| Memory management | Built-In | Manual |
| Memory bandwidth | 1-Gbps SDRAM | 9.5-Gbps DDRII ² |
| Power consumption (for high-end processing devices) | Low per device (high per computation) | High per device (low per computation) |

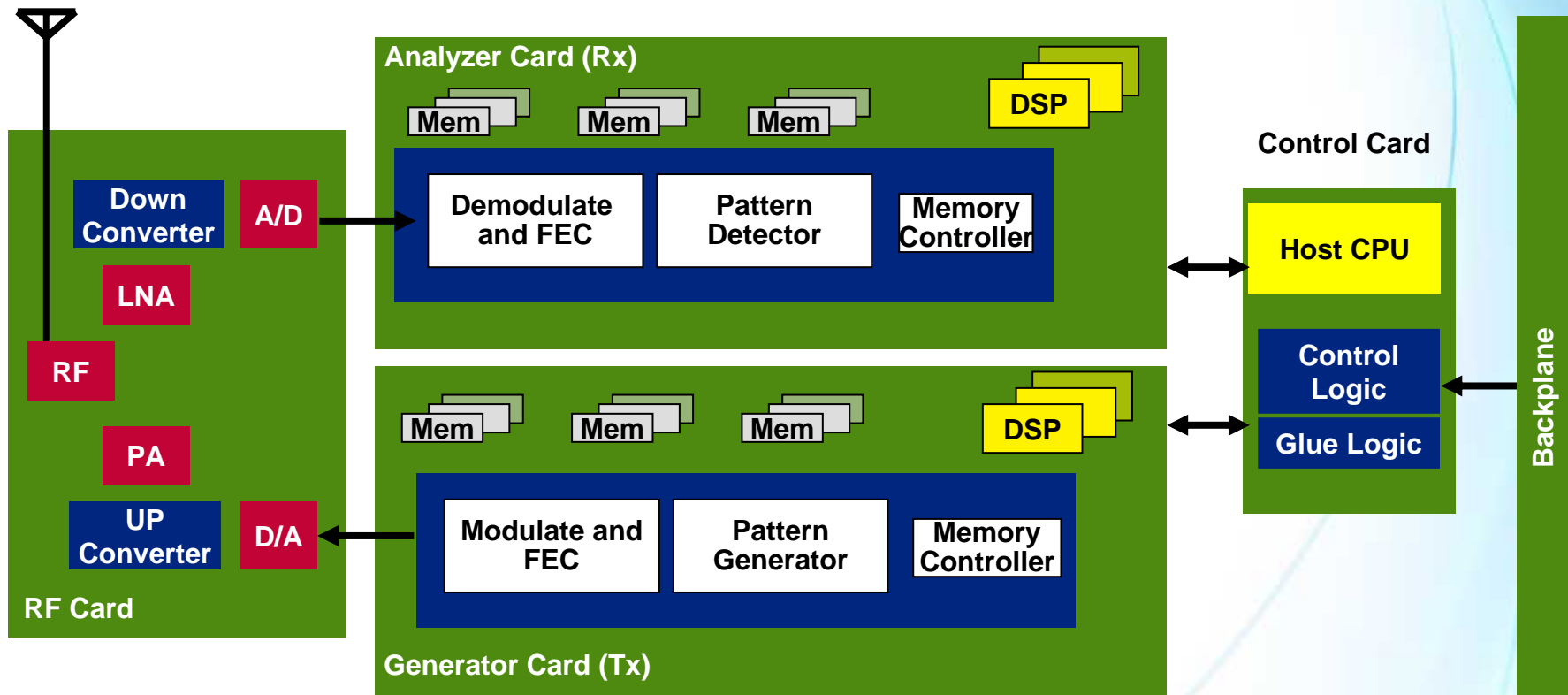
(1) Multipliers Can Be Implemented Using Hardware (HW) Based Multipliers & Logic Element (LE) Based Multipliers.

(2) Other Memory Interfaces are Supported Including Single Data Rate, Double Data Rate, RLDRAMII, QDR & QDRII

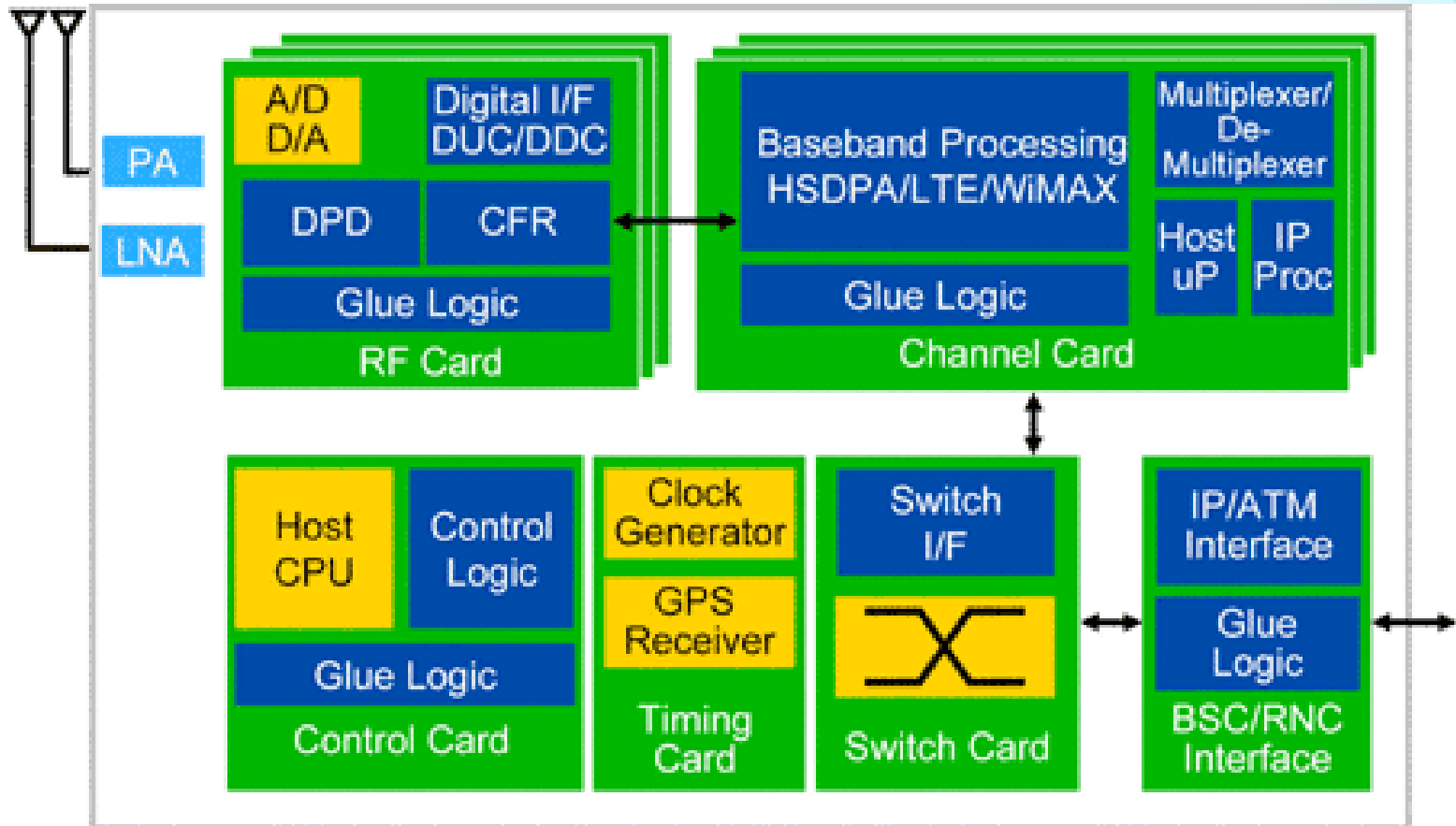
Datapath Processing Architecture Options



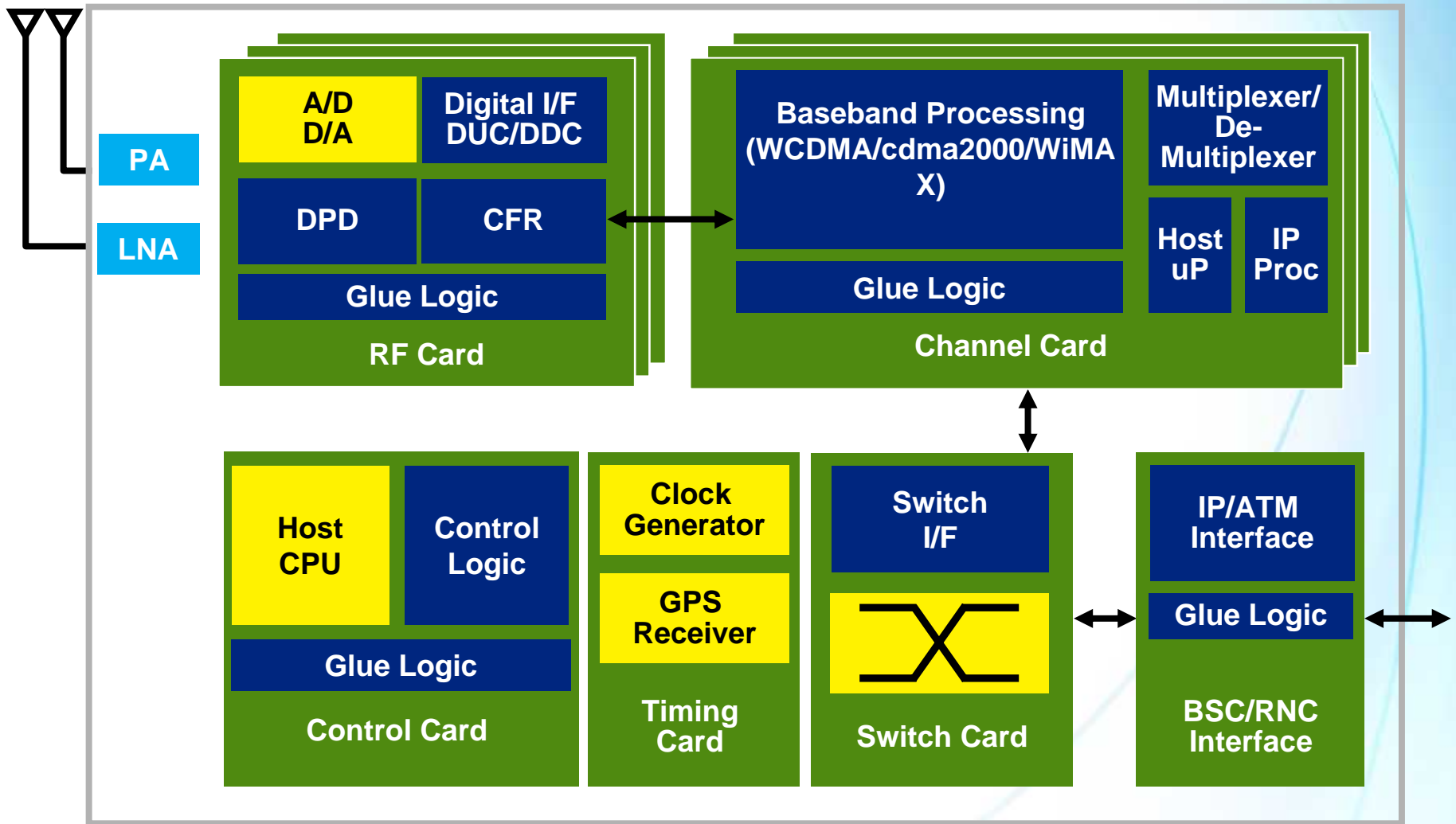
Example: Wireless Tester



Example: WiMAX Channel Card



Example: WiMAX Channel Card



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Serial RapidIO Review

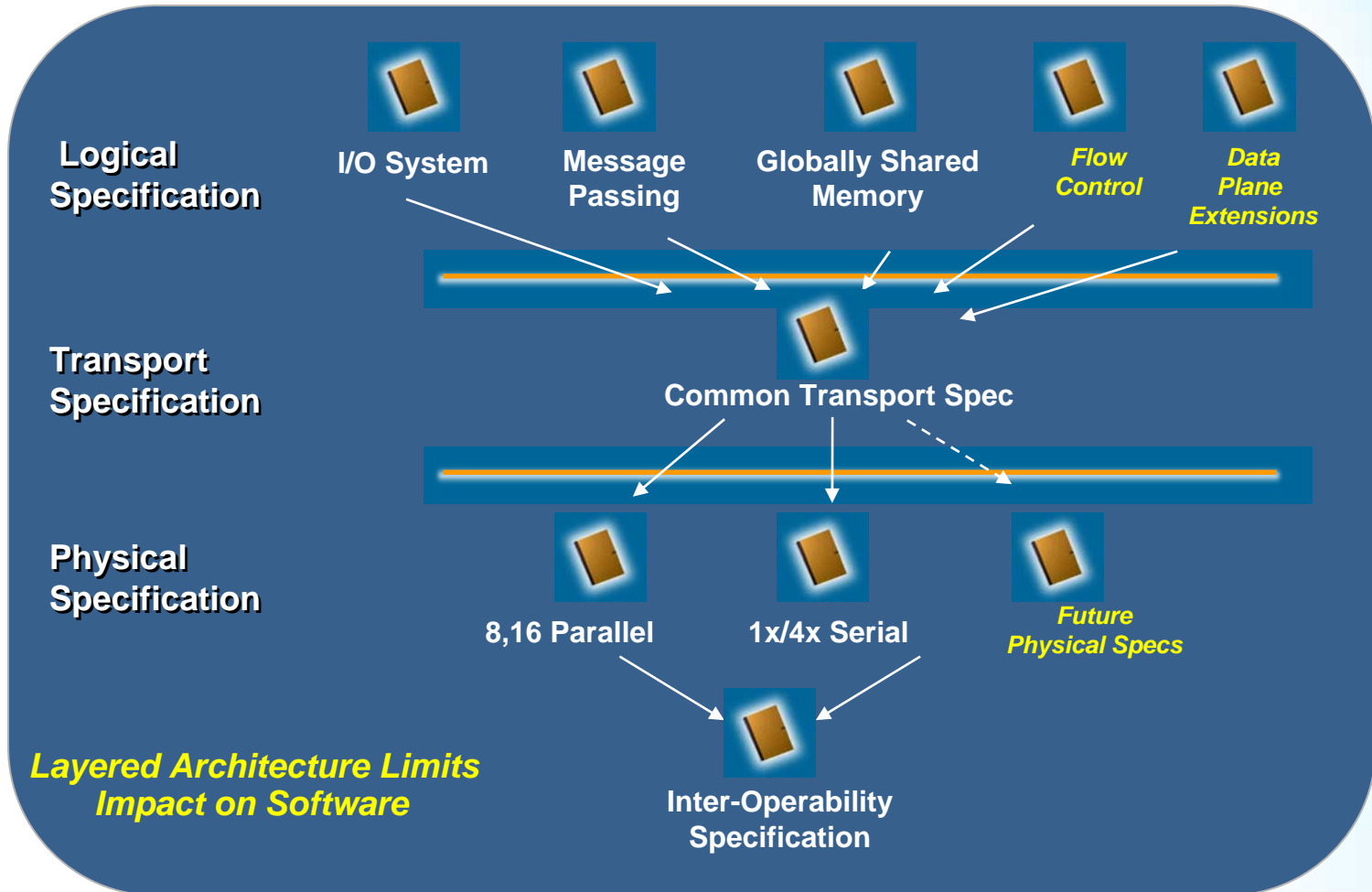


Interconnect Technology Review

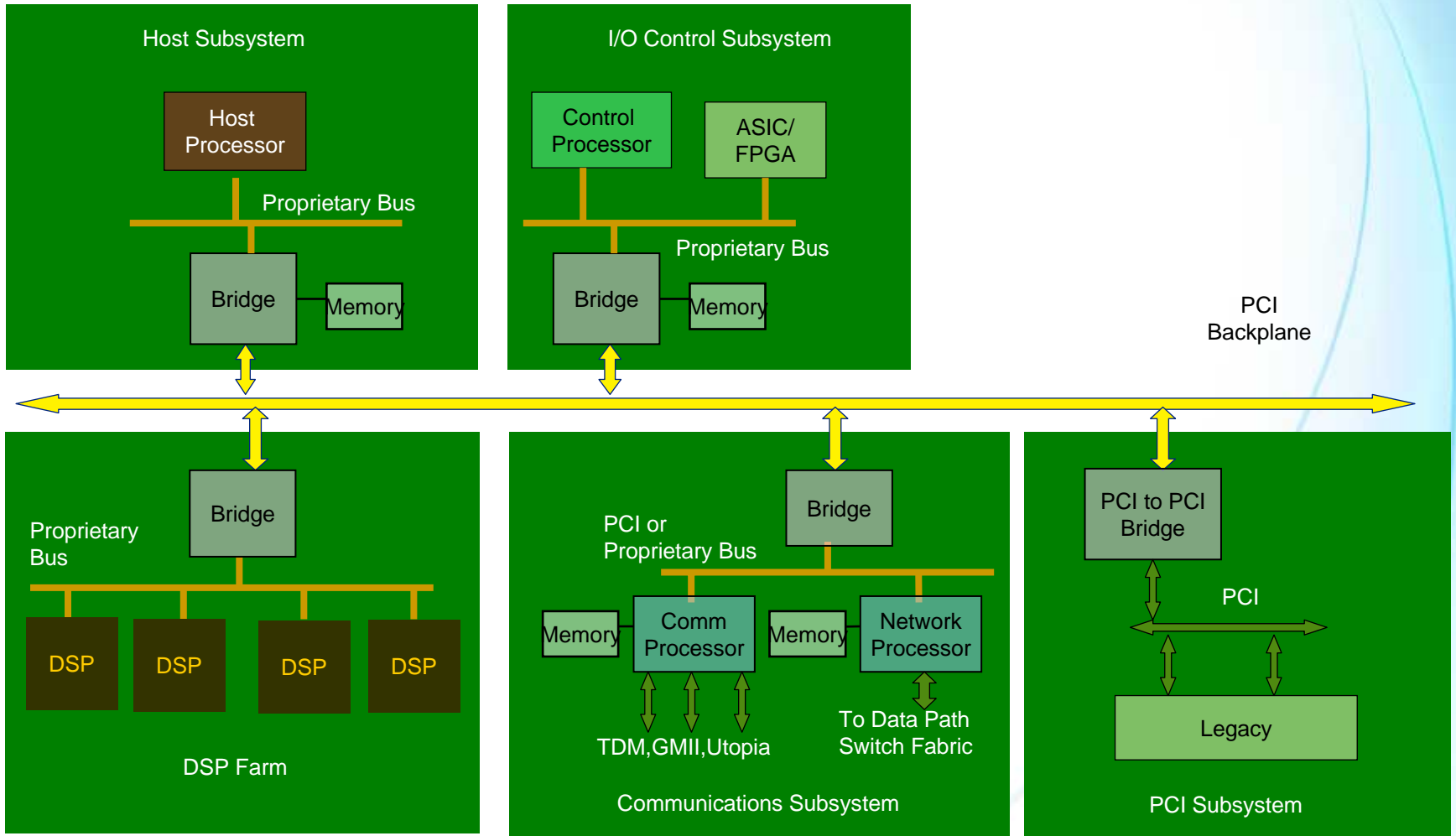
| <i>Interconnect Use</i> | | <i>Characteristics</i> | |
|-------------------------------|-----------|------------------------|--|
| LAN/WAN | | Ethernet | <i>IPv4/IPv6, 48-bit MAC Address</i> |
| Traffic-Managed Fabric | | RapidIO | <i>Hundreds of classes, millions of flows, end-to-end flow control, interworking, scalable</i> |
| Switched Interconnect | | ASI | <i>Message passing, architectural/topological independence, one flow, protocol tunneling</i> |
| Serial Local Bus | | PCI Express | <i>Serialized Input/Output Transactions/DMA</i> |
| Parallel Local Bus | HT | PCI-X | <i>Parallel Input/Output Transactions/DMA</i> |



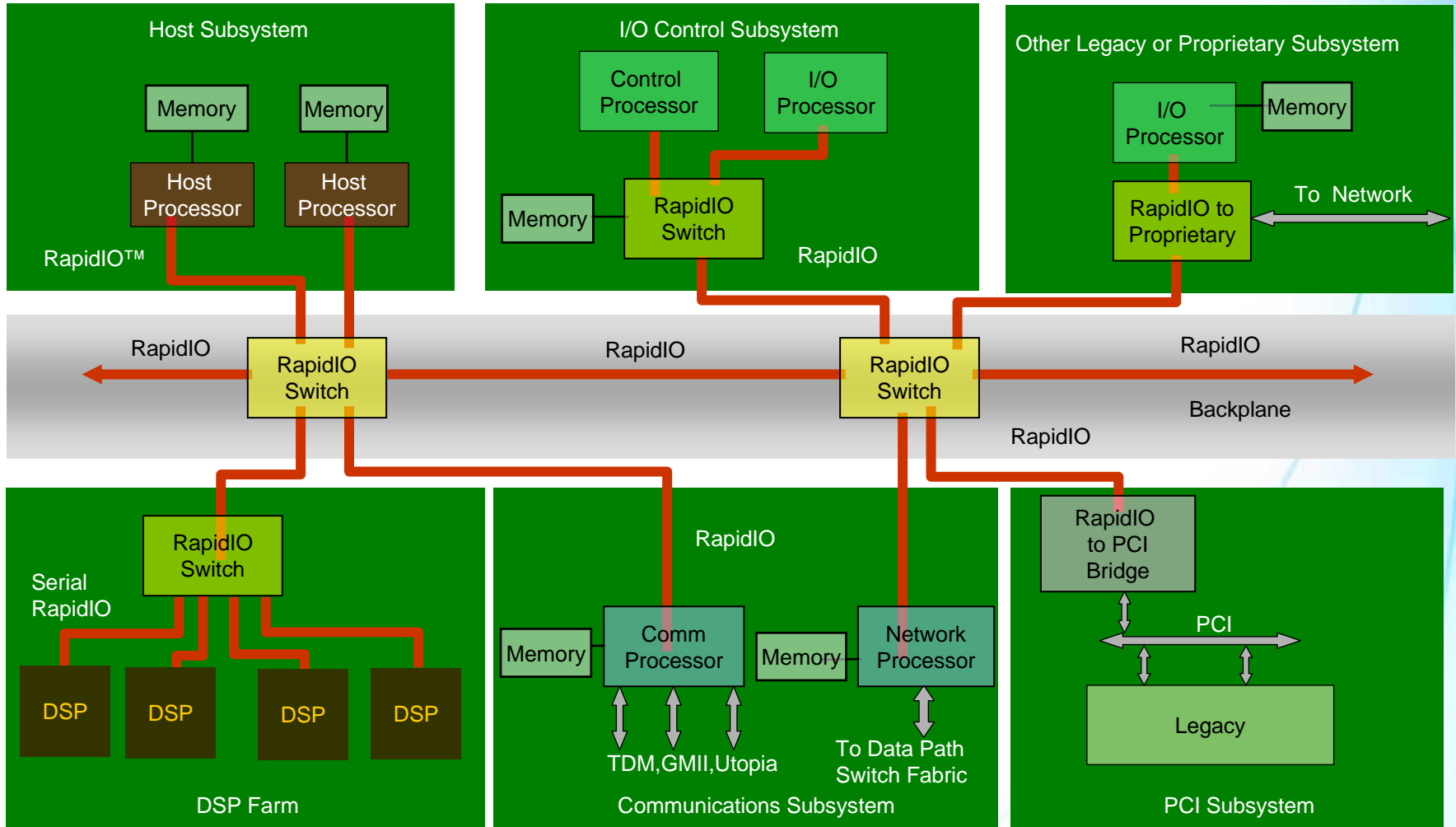
RapidIO Hierarchy



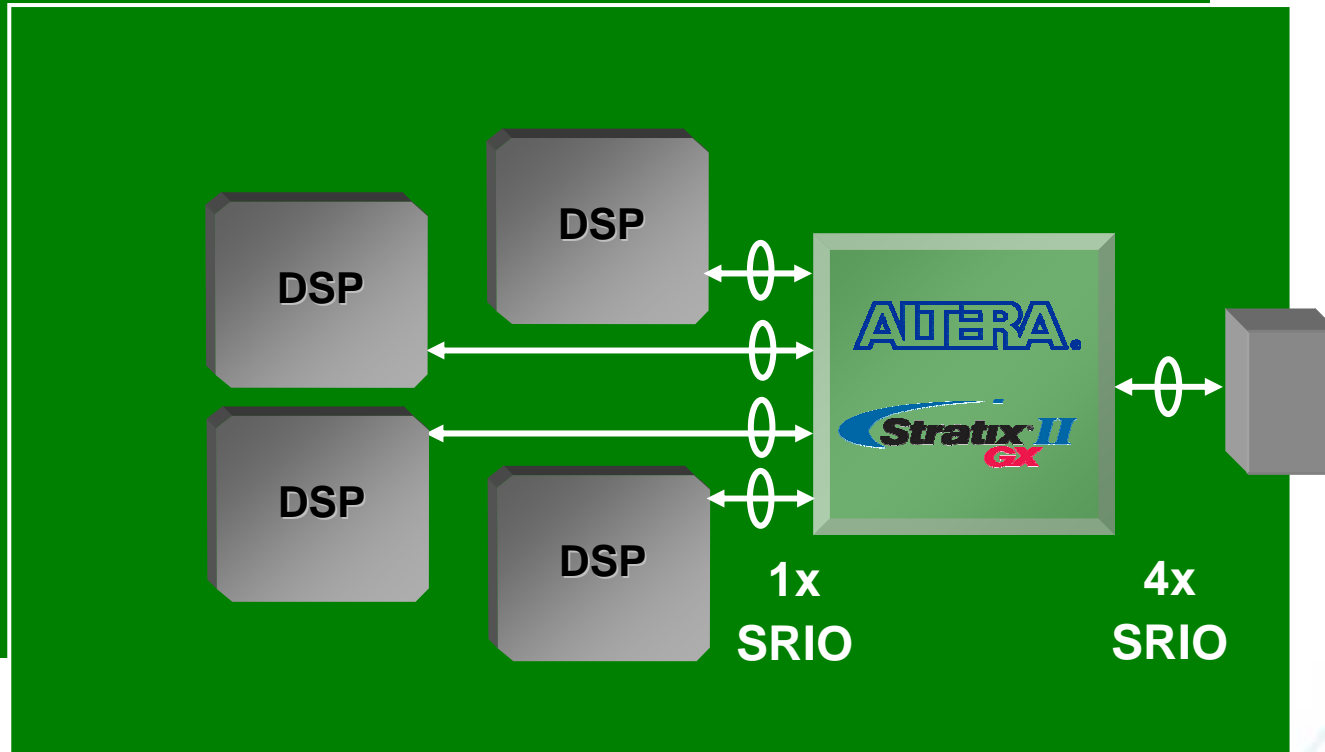
Traditional Interconnect Architecture



RapidIO Systems

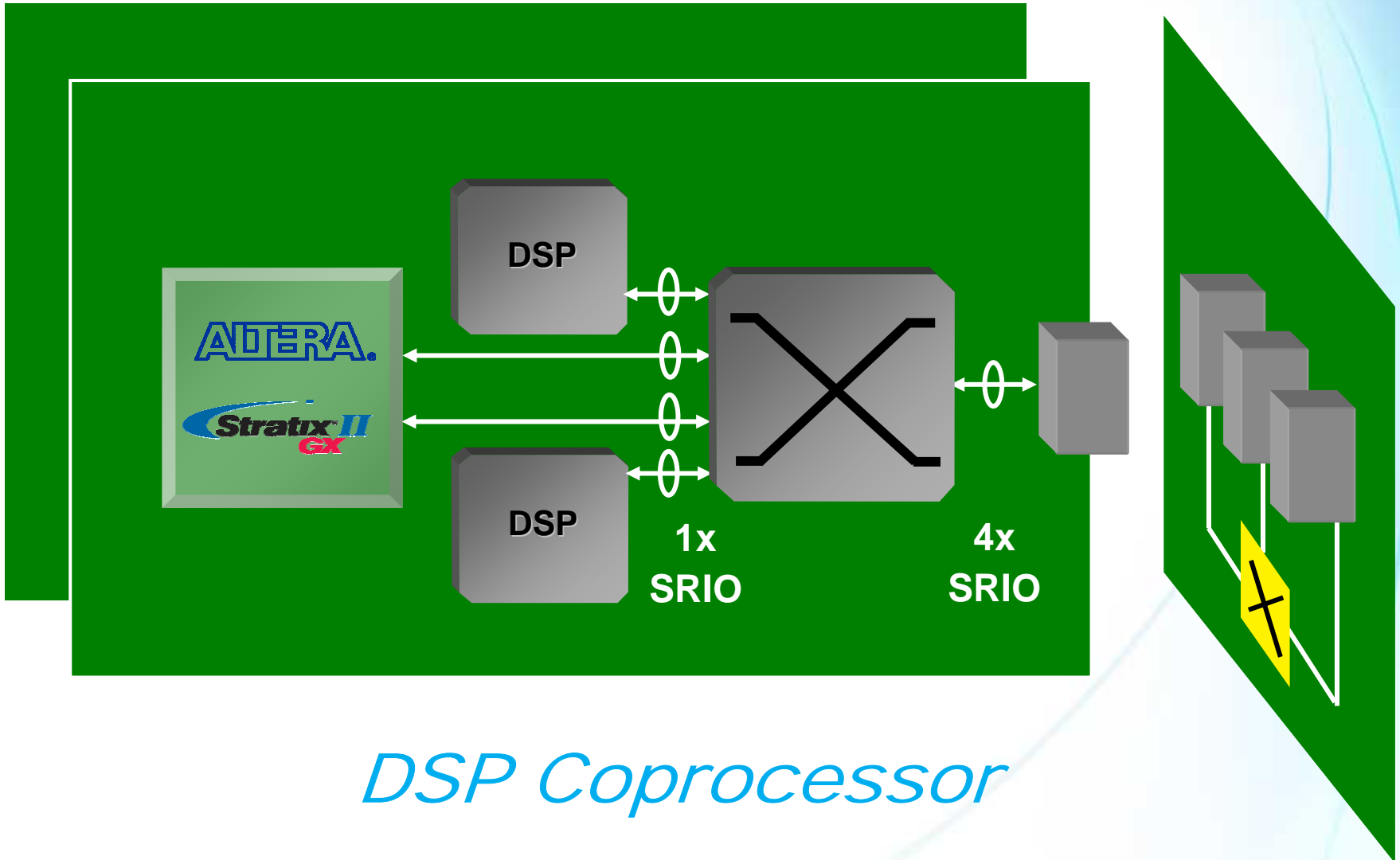


Typical Application



*DSP Farm Switch and
Backplane Interconnect*

Typical Application



DSP Coprocessor

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Altera Serial RapidIO Solution



Altera Stratix II GX RapidIO Solution

- RapidIO MegaCore® Version 6.1
- Compliant with RapidIO Trade Association, *RapidIO Interconnect Specification*, Revision 1.3
- Physical layer features
 - 1x/4x serial
 - Stratix® II GX support, including 1x and 4x up to 3.125 Gbps
 - Cyclone® II, Stratix II, Stratix III, and HardCopy® II support with an XGMII-like interface to a high-speed full-duplex, serializer / deserializer (SERDES) transceiver
 - 8-bit parallel
- Transport layer features
 - Supports multiple logical layer modules
 - Supports 8-bit device identities (IDs)
 - Device IDs, addressable CARs, and CSRs eliminate hop-count handling and CRC recomputing
- Logic layer features
 - Maintenance master and slave logical layer module
 - I/O master and slave logical layer module
 - Doorbell support
- PCI Express development kit expansion via HSMC connectors to AMC module
- SRIO loopback example design available based on the signal integrity kit
- Other IP vendors: Mercury Computers, GDA Technologies, Jennic, Preasum

SRIO Stratix II GX Characterization

- SRIO I/O (*PMA*) specifications have evolved
 - Currently identical to XAUI @ 3.125 Gbps
 - Currently identical to Gigabit Ethernet @ 1.25 Gbps and 2.5 Gbps
- Stratix II GX passes SRIO characterization spectacularly at 3.125 Gbps
- The XAUI and SRIO characterization report now available

Interoperability

- Stratix II GX with Altera MegaCore interoperability with TI DSP device via SRIO
 - Stratix II GX signal integrity (SI) board to TI DSP 6455 board via an SMA breakout board

| Number of Lanes | Baud Rate (Gbaud) | Internal Data Path Width |
|-----------------|-------------------|--------------------------|
| X1 | 1.25 | 32 |
| X1 | 2.5 | 32 |
| X1 | 3.125 | 32 |
| X4 | 2.5 | 64 |
| X4 | 3.125 | 64 |

- Interoperability with IDT switch x1 @ 3.125 Gbps
- Bittware AMC board with Stratix II GX interoperability with TI DSPs via Tundra passed

Stratix II GX FPGA-based Serial RapidIO Solution

| Item | Status |
|---|--------|
| Stratix II GX FPGA | ✓ |
| IP core (x1, x4 serial, x8 parallel) | ✓ |
| Development kit | ✓ |
| Reference designs | ✓ |
| Device characterization report | ✓ |
| System validation report | ✓ |
| Additional interoperability (Texas Instruments) | ✓ |

Summary

- Serial RapidIO has become the interface of choice for high-performance DSP applications
- Altera offers complete, easy-to-use Serial RapidIO solutions
 - Arria™ GX FPGAs for mainstream applications
 - Stratix II GX FPGAs for high-performance systems
- Low-risk, hardware-verified solutions
 - Stratix II GX interoperability with Texas Instruments
 - Development boards

*Fastest Time-To-Market with
Reliable RapidIO Solutions*

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Serial RapidIO Demo

